

WLCSP20 1.96x1.87x0.586 CASE 567SL **ISSUE O** DATE 30 NOV 2016 Æ BALL A1 Α Е 1.20 1.20 INDEX AREA Ø0.20 Ø0.215 В A1 Cu Pad Cu Pad  $\bigcirc \bigcirc \bigcirc \bigcirc$ ◗◑Đ៙ 0.03 C 000 0000 2X ⊕⊘⊘⊕ 1.60  $\Theta O O \Theta$ 0.40 Ø0.315 Solder Ø0.30 Solder 0000  $\oplus 000$ D Mask Opening Mask Opening  $\oplus \oplus \bigcirc \bigcirc$  $\Theta \Theta O O$ - 0.40 - 0.40 option 1 option 2 0.03 C 2X **RECOMMENDED LAND PATTERN** TOP VIEW (NSMD TYPE) // 0.06 C -0.378±0.018 0.625 Æ 0.05 C 0.547 0.208±0.021 0000 С SEATING PLANE А SIDE VIEWS NOTES: ⊕ 0.005 (M) C A B 1.20 Ø0.260±0.02 A. NO JEDEC REGISTRATION APPLIES. 0.40 20X **B. DIMENSIONS ARE IN MILLIMETERS.** Ð ⊕lO ∯ Е C. DIMENSIONS AND TOLERANCE 0000 D PER ASMEY14.5M, 2009. 1.60 0000 С D. DATUM C IS DEFINED BY THE SPHERICAL -⊕ O O O В - (Y) ±0.018 CROWNS OF THE BALLS. 0.40 🕀 OiO 🕀 /E\PACKAGE NOMINAL HEIGHT IS 586 MICRONS Æ ±39 MICRONS (547-625 MICRONS). 2 3 1 (X) ±0.018 /F.\ FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET. BOTTOM VIEW

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